

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|---|------|------|---|--|------------------|----------|------------------|--------|
| 1 | BRS | 22 | electrode and flexible with reinforcement with bond\$3 and adhesive with flexible | USPAT; US-PGPU B; EPO; JPO; DERWENT; IBM_TDB | 2003/05/31 19:24 | | | 0 |
| 2 | BRS | 130 | electrode with bump and flexible with bond\$3 and adhesive with flexible | USPAT; US-PGPU B; EPO; JPO; DERWENT; IBM_TDB | 2003/05/12 22:33 | | | 0 |
| 3 | BRS | 1 | electrode with bump and flexible with bond\$3 and adhesive with flexible and dic\$3 with groove | USPAT; US-PGPU B; EPO; JPO; DERWENT; IBM_TDB | 2003/05/12 22:34 | | | 0 |
| 4 | BRS | 22 | electrode with bump and flexible with bond\$3 and adhesive with flexible and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT; IBM_TDB | 2003/05/12 22:51 | | | 0 |
| 5 | BRS | 12 | electrode with bump and flexible with bond\$3 and adhesive with resin and adhesive with flexible and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT; IBM_TDB | 2003/05/12 22:52 | | | 0 |
| 6 | IS&R | 2 | ("5637800"). PN. | USPAT; US-PGPU B; EPO; JPO; DERWENT; IBM_TDB | 2003/05/30 17:13 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|------|------|--|---|---------------------|----------|------------------|--------|
| 7 | BRS | 6 | 5637800.URPN. | USPAT | 2003/05/30 17:10 | | | 0 |
| 8 | IS&R | 2 | ("4965653").PN. | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 17:18 | | | 0 |
| 9 | BRS | 10 | 4965653.URPN. | USPAT | 2003/05/30 17:14 | | | 0 |
| 10 | IS&R | 2 | ("6280828").PN. | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 17:20 | | | 0 |
| 11 | BRS | 1 | 6280828.URPN. | USPAT | 2003/05/30 17:18 | | | 0 |
| 12 | BRS | 3 | ("5372871" "5621333" "5864470").PN. | USPAT | 2003/05/30 17:19 | | | 0 |
| 13 | BRS | 1978 | "flexible wiring board" | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/31 21:55 | | | 0 |
| 14 | BRS | 444 | "flexible wiring board" and electrode | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 17:21 | | | 0 |
| 15 | BRS | 154 | "flexible wiring board" and electrode and adhesive | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 20:05 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|------|------|--|---|-------------------------|----------|------------------|--------|
| 16 | BRS | 3 | "flexible wiring board" and electrode and adhesive and reinforc\$3 and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 17:24 | | | 0 |
| 17 | BRS | 30 | "flexible wiring board" and electrode and adhesive and reinforc\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 20:04 | | | 0 |
| 18 | BRS | 4 | "flexible wiring board" and electrode and adhesive with carrier | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 17:50 | | | 0 |
| 19 | BRS | 3 | "flexible wiring board" and electrode and adhesive and reinforc\$3 and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 20:05 | | | 0 |
| 20 | BRS | 21 | "flexible wiring board" and electrode and adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 20:38 | | | 0 |
| 21 | BRS | 2 | bump with front with surface and reinforcement with back with surface with adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 21:11 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|------|------|---|---|------------------|----------|------------------|--------|
| 22 | BRS | 2 | pad with front with surface and reinforcement with back with surface with adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 21:11 | | | 0 |
| 23 | BRS | 3 | reinforcement with back with surface with adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 22:47 | | | 0 |
| 24 | BRS | 200 | circuit with board and back with surface with adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 21:20 | | | 0 |
| 25 | BRS | 79 | circuit with board and back with surface with adhesive with bond\$3 and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 21:20 | | | 0 |
| 26 | BRS | 25 | circuit with board and substrate with back with surface with adhesive with bond\$3 and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/31 21:09 | | | 0 |
| 27 | BRS | 4 | front with pad and substrate with back with surface with adhesive with bond\$3 and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 21:58 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|------|------|--|---|-------------------------|----------|------------------|--------|
| 28 | BRS | 1 | front with pad and substrate with back with surface with adhesive with bond\$3 and dicing | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 21:59 | | | 0 |
| 29 | BRS | 1 | pad and substrate with back with surface with adhesive with bond\$3 and dicing and etch\$3 with back with wafer | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:12 | | | 0 |
| 30 | BRS | 1 | bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and etch\$3 with back with wafer | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:14 | | | 0 |
| 31 | BRS | 2 | bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and polish\$3 with back with wafer | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:14 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|------|------|--|---|------------------|----------|------------------|--------|
| 32 | BRS | 1 | bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and remov\$3 with back with wafer | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 22:15 | | | 0 |
| 33 | BRS | 2 | bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and grind\$3 with back with wafer | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 22:21 | | | 0 |
| 34 | BRS | 3 | 6184064.URPN . | USPAT | 2003/05/30 22:16 | | | 0 |
| 35 | BRS | 1 | bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and thin\$4 with back with wafer | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 22:27 | | | 0 |
| 36 | IS&R | 2 | ("6429506"). PN. | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 22:27 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|------|------|---|---|-------------------------|----------|------------------|--------|
| 37 | BRS | 2 | reinforc\$5 with hold\$3 same hand\$4 and surface with adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:50 | | | 0 |
| 38 | BRS | 2 | reinforc\$5 with hold\$3 same hand\$4 and semiconductor and adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:51 | | | 0 |
| 39 | BRS | 15 | pad and flexible with reinforc\$3 and wafer with dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/31 19:25 | | | 0 |
| 40 | BRS | 9 | electrode and flexible with reinforc\$3 and wafer with dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/31 19:42 | | | 0 |
| 41 | BRS | 4 | bond with pad and adhesive and flexible with reinforc\$3 and wafer with dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/31 19:47 | | | 0 |
| 42 | BRS | 46 | bond with pad and adhesive with flexible with substrate and wafer with dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/31 20:26 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|------|------|---|---|-------------------------|----------|------------------|--------|
| 43 | BRS | 27 | bond and pad and ball and adhesive with flexible with substrate and wafer with dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/31 20:27 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|---|----------|------|--|---|-------------------------|----------|------------------|--------|
| 1 | BRS | 22 | electrode and flexible with reinforc\$3 with bond\$3 and adhesive with flexible | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/31 19:24 | | | 0 |
| 2 | BRS | 130 | electrode with bump and flexible with bond\$3 and adhesive with flexible | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/12 22:33 | | | 0 |
| 3 | BRS | 1 | electrode with bump and flexible with bond\$3 and adhesive with flexible and dic\$3 with groove | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/12 22:34 | | | 0 |
| 4 | BRS | 22 | electrode with bump and flexible with bond\$3 and adhesive with flexible and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/12 22:51 | | | 0 |
| 5 | BRS | 12 | electrode with bump and flexible with bond\$3 and adhesive with resin and adhesive with flexible and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/12 22:52 | | | 0 |
| 6 | IS& R | 2 | ("5637800"). PN. | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 17:13 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|------|------|--|---|------------------|----------|------------------|--------|
| 7 | BRS | 6 | 5637800.URPN . | USPAT | 2003/05/30 17:10 | | | 0 |
| 8 | IS&R | 2 | ("4965653").PN. | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 17:18 | | | 0 |
| 9 | BRS | 10 | 4965653.URPN . | USPAT | 2003/05/30 17:14 | | | 0 |
| 10 | IS&R | 2 | ("6280828").PN. | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 17:20 | | | 0 |
| 11 | BRS | 1 | 6280828.URPN . | USPAT | 2003/05/30 17:18 | | | 0 |
| 12 | BRS | 3 | ("5372871" "5621333" "5864470").PN. | USPAT | 2003/05/30 17:19 | | | 0 |
| 13 | BRS | 1978 | "flexible wiring board" | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/31 21:55 | | | 0 |
| 14 | BRS | 444 | "flexible wiring board" and electrode | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 17:21 | | | 0 |
| 15 | BRS | 154 | "flexible wiring board" and electrode and adhesive | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 20:05 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|------|------|--|---|---------------------|----------|------------------|--------|
| 16 | BRS | 3 | "flexible wiring board" and electrode and adhesive and reinforc\$3 and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 17:24 | | | 0 |
| 17 | BRS | 30 | "flexible wiring board" and electrode and adhesive and reinforc\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 20:04 | | | 0 |
| 18 | BRS | 4 | "flexible wiring board" and electrode and adhesive with carrier | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 17:50 | | | 0 |
| 19 | BRS | 3 | "flexible wiring board" and electrode and adhesive and reinforc\$3 and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 20:05 | | | 0 |
| 20 | BRS | 21 | "flexible wiring board" and electrode and adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 20:38 | | | 0 |
| 21 | BRS | 2 | bump with front with surface and reinforcement with back with surface with adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 21:11 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|------|------|---|---|------------------|----------|------------------|--------|
| 22 | BRS | 2 | pad with front with surface and reinforcement with back with surface with adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 21:11 | | | 0 |
| 23 | BRS | 3 | reinforcement with back with surface with adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 22:47 | | | 0 |
| 24 | BRS | 200 | circuit with board and back with surface with adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 21:20 | | | 0 |
| 25 | BRS | 79 | circuit with board and back with surface with adhesive with bond\$3 and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 21:20 | | | 0 |
| 26 | BRS | 25 | circuit with board and substrate with back with surface with adhesive with bond\$3 and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/31 21:09 | | | 0 |
| 27 | BRS | 4 | front with pad and substrate with back with surface with adhesive with bond\$3 and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/05/30 21:58 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|------|------|--|---|-------------------------|----------|------------------|--------|
| 28 | BRS | 1 | front with pad and substrate with back with surface with adhesive with bond\$3 and dicing | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 21:59 | | | 0 |
| 29 | BRS | 1 | pad and substrate with back with surface with adhesive with bond\$3 and dicing and etch\$3 with back with wafer | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:12 | | | 0 |
| 30 | BRS | 1 | bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and etch\$3 with back with wafer | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:14 | | | 0 |
| 31 | BRS | 2 | bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and polish\$3 with back with wafer | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:14 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|----------|------|---|---|-------------------------|----------|------------------|--------|
| 32 | BRS | 1 | bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and remov\$3 with back with wafer | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:15 | | | 0 |
| 33 | BRS | 2 | bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and grind\$3 with back with wafer | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:21 | | | 0 |
| 34 | BRS | 3 | 6184064.URPN . | USPAT | 2003/0 5/30 22:16 | | | 0 |
| 35 | BRS | 1 | bond adj pad and substrate and back with surface with adhesive with bond\$3 and dicing and thin\$4 with back with wafer | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:27 | | | 0 |
| 36 | IS& R | 2 | ("6429506"). PN. | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:27 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|------|------|---|---|-------------------------|----------|------------------|--------|
| 37 | BRS | 2 | reinforc\$5 with hold\$3 same hand\$4 and surface with adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:50 | | | 0 |
| 38 | BRS | 2 | reinforc\$5 with hold\$3 same hand\$4 and semiconductor and adhesive and dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/30 22:51 | | | 0 |
| 39 | BRS | 15 | pad and flexible with reinforc\$3 and wafer with dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/31 19:25 | | | 0 |
| 40 | BRS | 9 | electrode and flexible with reinforc\$3 and wafer with dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/31 19:42 | | | 0 |
| 41 | BRS | 4 | bond with pad and adhesive and flexible with reinforc\$3 and wafer with dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/31 19:47 | | | 0 |
| 42 | BRS | 46 | bond with pad and adhesive with flexible with substrate and wafer with dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/31 20:26 | | | 0 |

| | Type | Hits | Search Text | DBs | Time Stamp | Comments | Error Definition | Errors |
|----|------|------|---|---|-------------------------|----------|------------------|--------|
| 43 | BRS | 27 | bond and pad and ball and adhesive with flexible with substrate and wafer with dic\$3 | USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB | 2003/0 5/31 20:27 | | | 0 |